Optical Science and Technology Center
Microfabrication Facility
Nanotechnology Training

Short course and Hands-on Training

ATOMIC LAYER DEPOSITION

Date and venue: Feb. 11, 9:30 am, IATL 104

Atomic Layer Deposition (ALD) is a “Nano” technology, allowing thin films of a few nanometers to be deposited in a precisely controlled way.

Atomic Layer Deposition (ALD) is a thin film deposition technique that is based on the sequential, self-limiting surface reaction based on the temporal separation of two or more reactants. Key Applications: high-k gate oxides, capacitors, solar cells, organic semiconductors, microfluidic, MEMS, Bio MEMS, memristors

Training details:
Lecture: 9:30 – 10:45 am
Outline: Intro. to Plasma and Thermal ALD techniques
  Overview of Oxford ALD Instruments
  ALD Processes
  Key Applications

Hands-on Lab: 11:00 – 1 pm (IATL 174)

Instructors: Shawn Xu Ph.D., (Process Engineer, Oxford Instruments America)
Aju Jugessur Ph.D., (Director, University of Iowa Microfabrication Facility)
Contact: aju-jugessur@uiowa.edu

REGISTER AT: http://ostc.uiowa.edu/ALD

Individuals with disabilities are encouraged to attend all University of Iowa-sponsored events. If you are a person with a disability who requires an accommodation in order to attend this program, please contact the Optical Science & Technology Center in advance at 353-0974 or email OSTC@uiowa.edu.